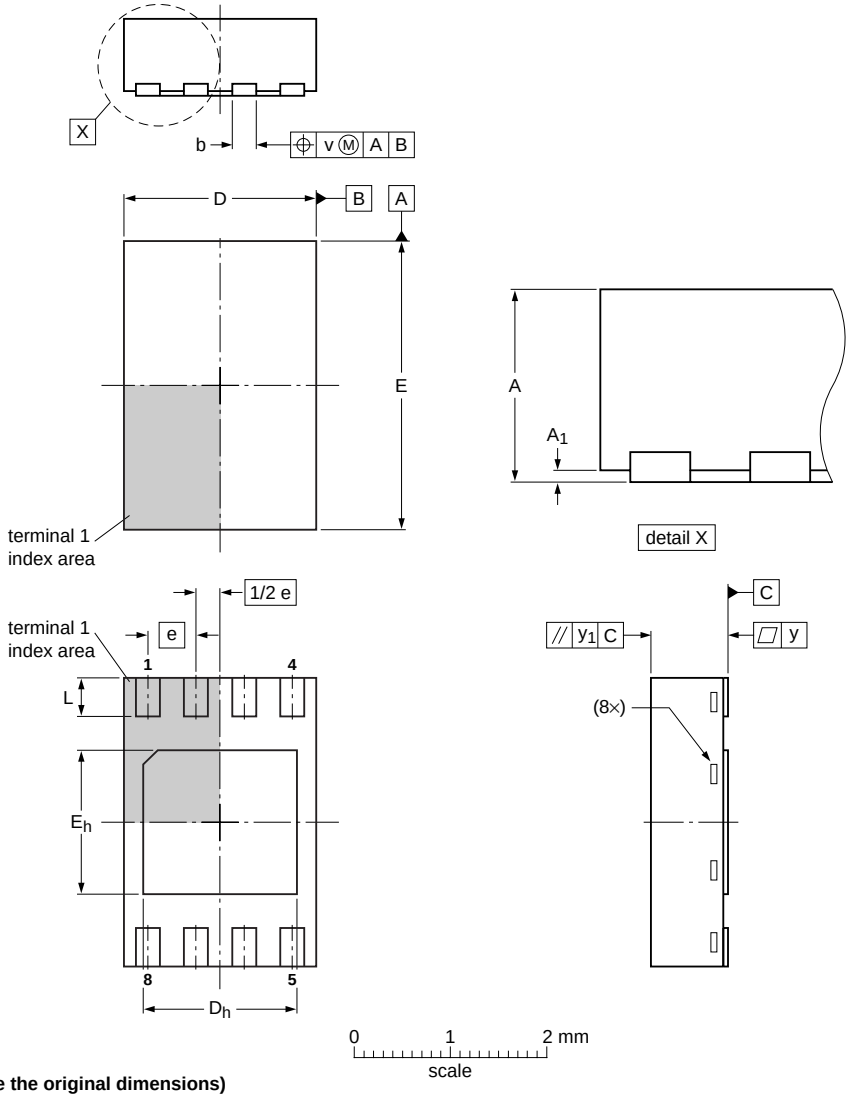
HWSON8: plastic thermal enhanced very very thin small outline package; no leads; 8 terminals; body 2 x 3 x 0.8 mm **SOT1069-1**



DIMENSIONS (mm are the original dimensions)

UNIT		A(1)	A_1	b	D	D_1	E	E_1	e	L	v	y	y_1
mm	max	0.8	0.04	0.3	2.1	1.6	3.1	1.6		0.45			
	nom				2.0		3.0		0.5		0.1	0.05	0.05
	min			0.2	1.9	1.4	2.9	1.4		0.35			

Note

1. Dimension A is including plating thickness. The package footprint is compatible with JEDEC MO229

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1069-1		MO-229				~~08-06-11~~ 08-07-10

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